

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Pulse Power Dissipation (Note 5) 10/1000µs (Note 6) 8/20µs	P _{PK}	225 1125	W
Peak Forward Surge Current, 8.3ms Single Half Sine Wave	I _{FSM}	35	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
DC Steady-State Power Dissipation (Note 8)	P _D	1.0	W
Thermal Resistance, Junction to Ambient (Note 8)	R _{θJA}	330	°C/W
Thermal Resistance, Junction to Soldering Point (Note 9)	R _{θJS}	70	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Part Number	Reverse Standoff Voltage	Breakdown Voltage V _{BR} @ I _T (Note 10)		Test Current	Max. Reverse Leakage @ V _{RWM}	Max. Clamping Voltage @ I _{PP}	Max. Peak Pulse Current (Note 5)	Marking Code
	V _{RWM} (V)	Min (V)	Max (V)	I _T (mA)	I _R (µA)	V _C (V)	I _{PP} (A)	
DPD13AWF	13	14.4	15.9	1.0	1.0	21.5	10.5	TBG

- Notes:
- Non-Repetitive current pulse as shown in figure 2 and derated above T_A = +25°C as per figure 2.
 - Non-Repetitive current pulse as shown in figure 3 and derated above T_A = +25°C as per figure 3.
 - 1/2 sine wave (or eTuivalent sTuare wave), pulse width = 8.3ms, duty cycle = 4 pulses/minute maximum.
 - Device mounted on 1"x1", FR-4 PCB; 2 oz. Cu pad layout. Cathode pad dimensions 5.5mm x 3.5mm. Anode pad dimensions 2.25mm x 3.5mm.
 - Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
 - V_{BR} measured at pulse test current I_T with tp ≤ 5.0ms at T_A = +25°C.

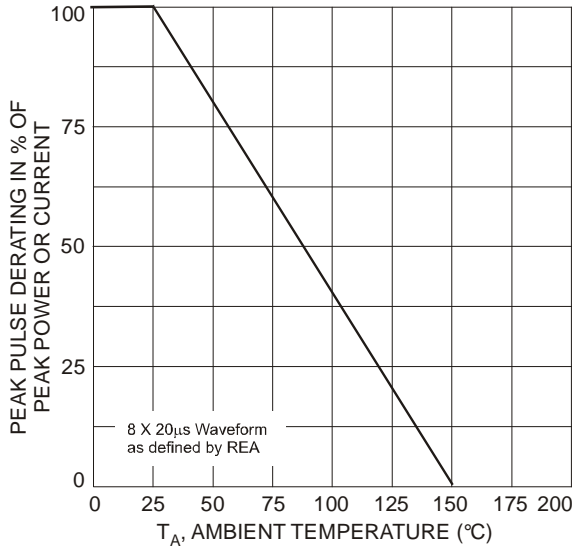


Fig. 1 Pulse Derating Curve

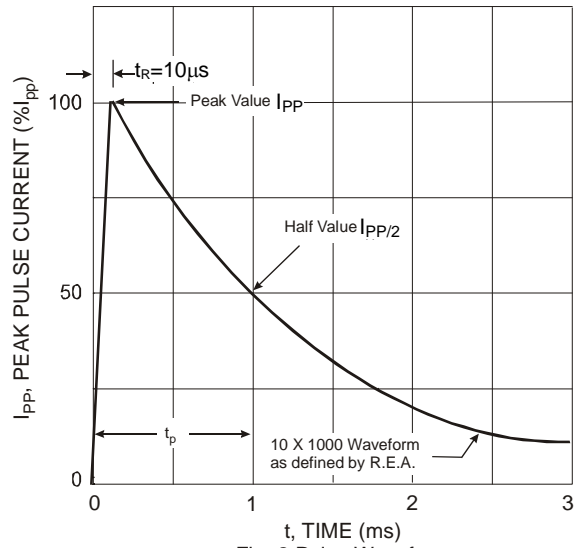


Fig. 2 Pulse Waveform

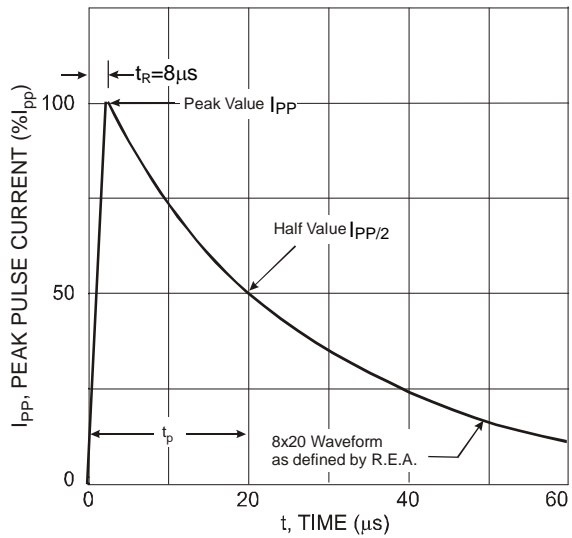


Fig. 3 Pulse Waveform

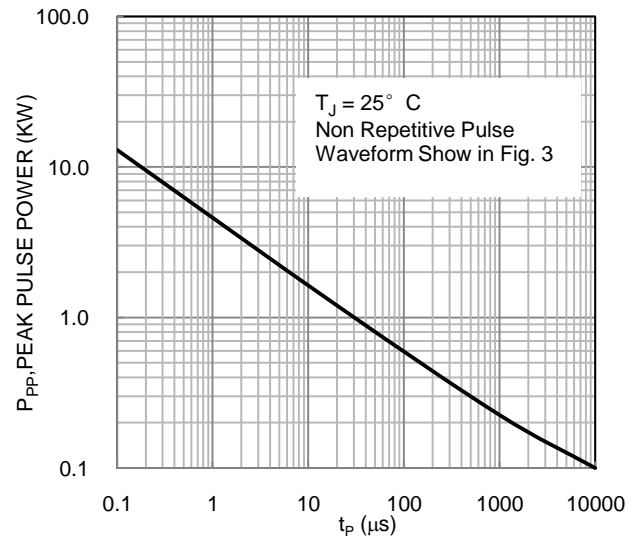


Fig. 4 Peak pulse power versus exponential pulse duration

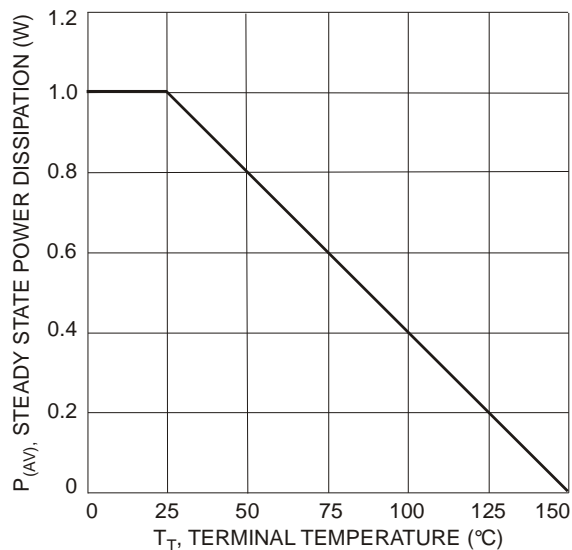


Fig. 5 Steady State Power Derating Curve

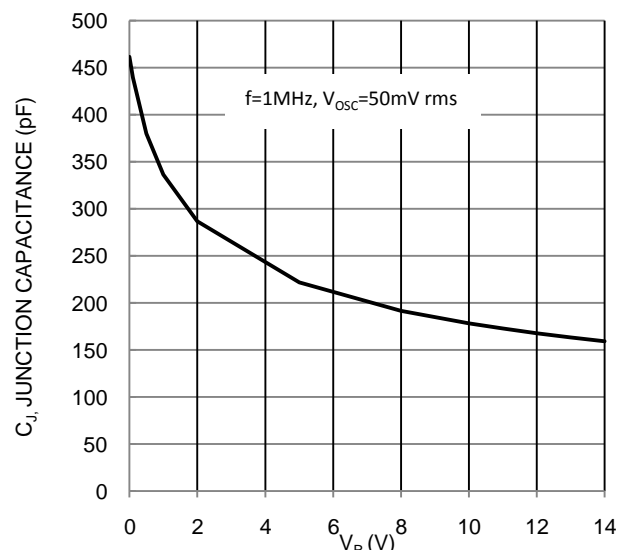
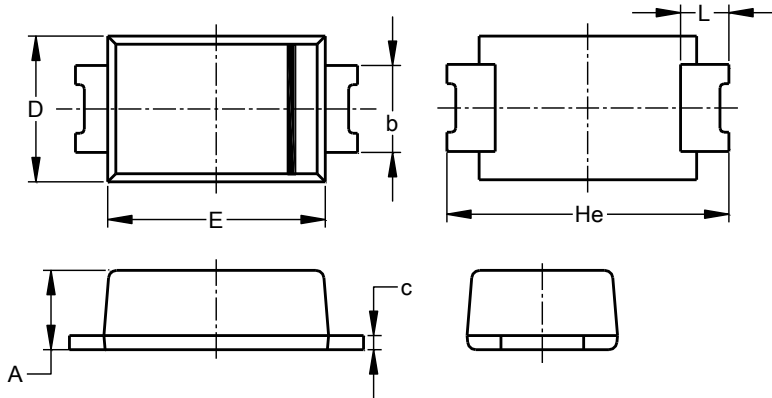


Fig. 6 Junction Capacitance versus Reverse Voltage

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOD123F (Type B)

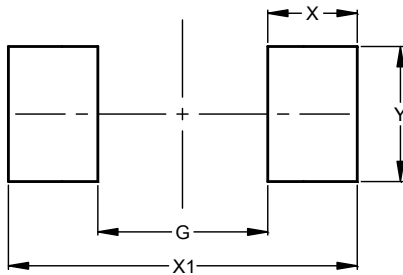


SOD123F (Type B)			
Dim	Min	Max	Typ
A	0.81	1.15	—
b	0.80	1.35	—
c	0.05	0.30	—
D	1.70	1.90	1.80
E	2.60	2.80	2.70
He	3.30	3.70	3.50
L	0.35	0.85	—
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOD123F (Type B)



Dimensions	Value (in mm)
G	1.90
X	1.00
X1	3.90
Y	1.50

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